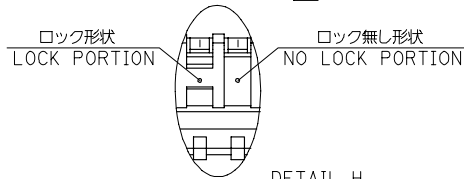
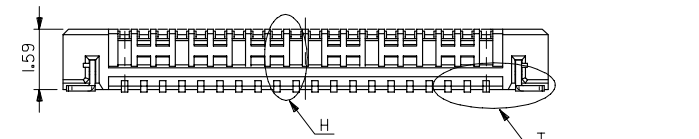
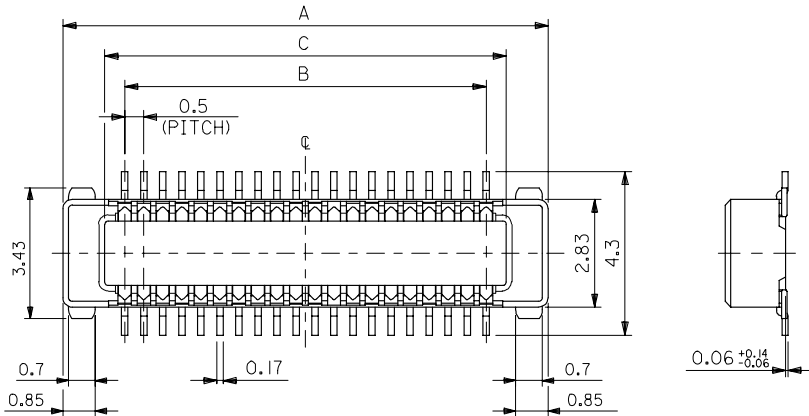


注記
NOTES:

1. 材質
MATERIAL
ハウジング: LCP (液晶ポリマー)、ガラス充填、黒色、UL94V-0
HOUSING: LCP (LIQUID CRYSTAL POLYMER), GLASS FILLED, BLACK, UL94V-0
ターミナル: 銅合金 (t=0.15)
TERMINAL: COPPER ALLOY (t=0.15)
ネイル: 銅合金 (t=0.15)
NAIL: COPPER ALLOY (t=0.15)
2. メッキ仕様
PLATING
ターミナル
TERMINAL
接点部: 金メッキ 0.25マイクロメートル以上
CONTACT AREA: GOLD 0.25 MICROMETER MINIMUM
半田付け部: 金メッキ 0.35マイクロメートル以下
SOLDER TAIL AREA: GOLD 0.35 MICROMETER MAXIMUM
下地メッキ: ニッケルメッキ 1.5マイクロメートル以上
UNDER PLATING: NICKEL 1.5 MICROMETER MINIMUM
ネイル
NAIL
銅メッキ 1.0マイクロメートル以上
TIN 1.0 MICROMETER MINIMUM
下地メッキ: ニッケルメッキ 1.0マイクロメートル以上
UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM
3. テール平坦度は、0.08ミリメートル以下。テールとネイルを併せた平坦度は、0.1ミリメートル以下。
TAIL COPLANARITY TO BE 0.08 MAXIMUM. TAILS AND NAILS COPLANARITY TO BE 0.1 MAXIMUM.
4. 嵌合相手: 54363-***
MATED CONN.: 54363-***
5. 本製品は55650-***1の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 55650-***1

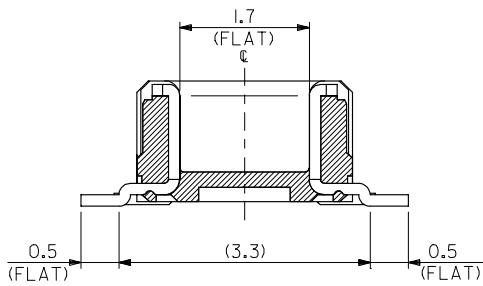


DETAIL H
SCALE 2:1

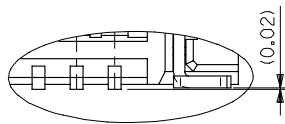
—#	28.05	27	30.25	55650-1181	110
4	18.05	17	20.25	55650-0781	70
8	15.55	14.5	17.75	55650-0681	60
12	13.05	12	15.25	55650-0581	50
20	10.55	9.5	12.75	55650-0481	40
30	8.05	7	10.25	55650-0381	30
20	5.55	4.5	7.75	55650-0281	20
ロック数 LOCKS	C	B	A	製品番号 MATERIAL NO.	極数 CIRCUITS

MODEL NO. 55650-***1

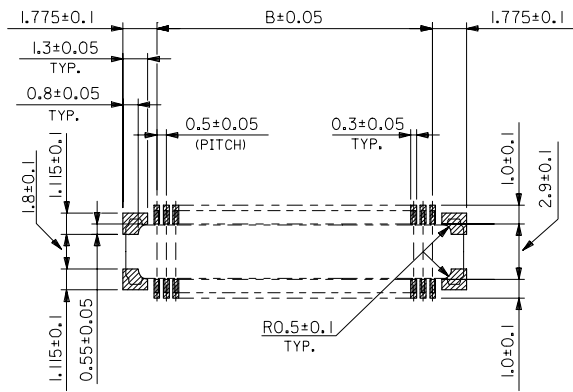
REVISED EC NO: J2008-0540 2007/09/03 DRAWN: YAOYAGI CHKD: KYODA 2007/09/03 APPR: NUKITA 2007/09/04	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY M. NAGATA	DATE 2004/03/09	TITLE 0.5 MM PITCH B/B CONN. PLUG NAIL ASS'Y (H=2MM) -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE 2004/03/09	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/03/09	DOCUMENT NO. SD-55650-013		
	ANGULAR ±3 °	MATERIAL NO. SEE TABLE		SHEET NO. 1 OF 2		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3				



製品断面図 (半田付け部、吸着面寸法)
DETAIL FOR SOLDERING AND VACUUM AREA



DETAIL T
T部図詳細

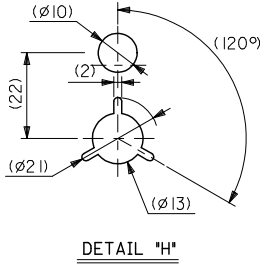
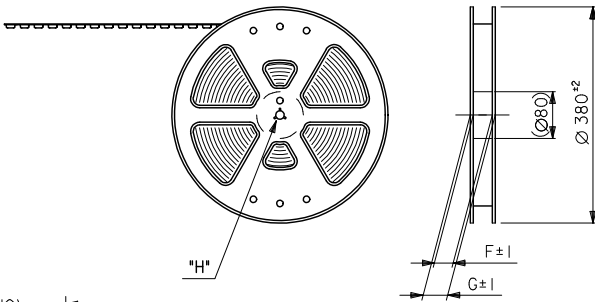


推奨基板寸法
RECOMMENDED PCB PATTERN LAYOUT
(SCALE 5:1)

REVISED EC NO: J2008-0540 2007/09/03 DRWN: YAOYAGI CHKD: KUYODA 2007/09/03 APPR: NUKITA 2007/09/04	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY M. NAGATA	DATE 2004/03/09	TITLE 0.5 MM PITCH B/B CONN. PLUG NAIL ASS'Y (H=2MM) -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE 2004/03/09	MOLEX MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/03/09	DOCUMENT NO. SD-55650-013		
B	DESCRIPTION	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE SHEET 1	SHEET NO. 2 OF 2		
		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

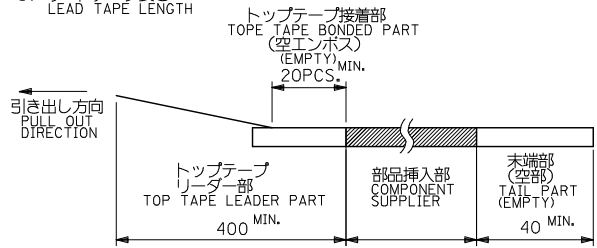
10 9 8 7 6 5 4 3 2 1

引き出し方向
PULL OUT DIRECTION



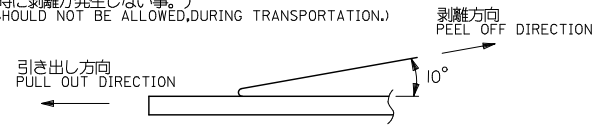
注)
NOTES

1. 製品番号55650-***81詳細寸法については、製品単体図面を参照下さい。
IN THE PACKAGE PART NUMBER 55650-***81 DETAILED DIMENSIONS, SEE SALES DRAWING FOR CONNECTOR.
2. 梱包数量:2500個/リール
NUMBER OF CONNECTORS:2500 PCS/REEL.
3. リードテープ長さ
LEAD TAPE LENGTH



4. トップテープの剥離強度: (剥離方向は下図参照)
PEELING OFF FORCE OF TOP TAPE (PELLING DIRECTION AS SHOWN IN FOLLOWING FIGURE.)
0. 1~1. 3N{10~130gf}

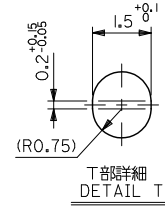
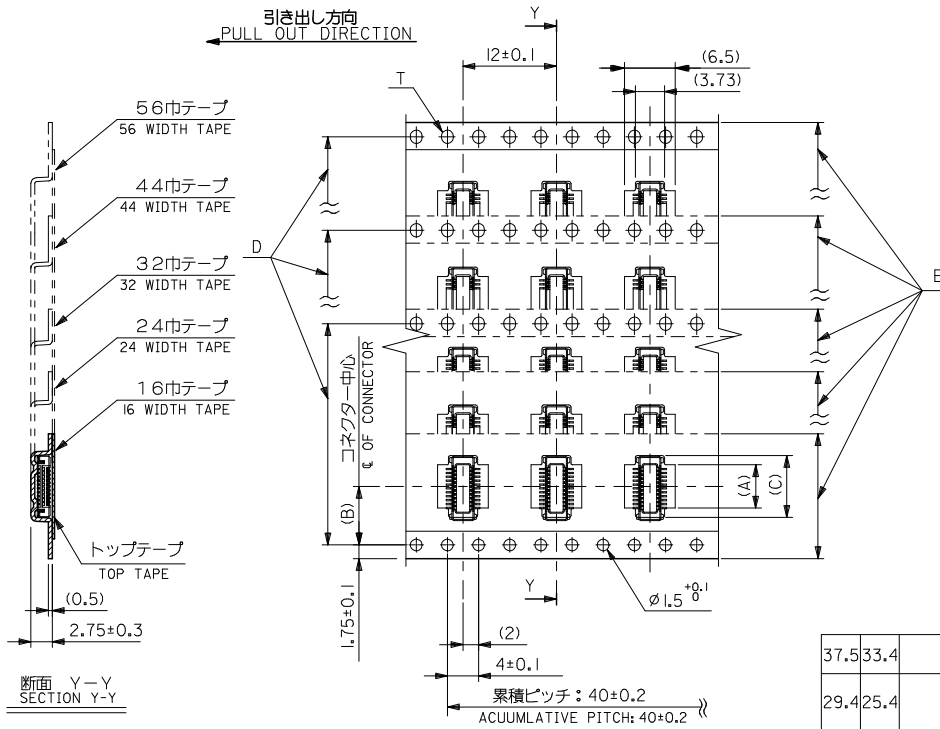
尚、本規格値は、出荷時に適用。
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
(但し、輸送時に剥離が発生しない事。)
(PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTATION.)



5. 材料
MATERIAL
キャリアテープ:ポリプロピレン (PP)
CARRIER TAPE:POLYPROPYLENE(PP)
トップテープ:PET, PE, PEF
TOP TAPE:PET,PE,PEF
リール:ポリスチレン (PS) <リサイクル材を含む>
REEL: POLYSTYRENE(PS) <RECYCLE MATERIAL CONTAINED>
6. 本製品は55650-***8の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 55650-***8

MATERIAL 材料	注記参照 SEE NOTES	REVISED EC NO: J2009-0552 DRAWN BY: JYOSHIDAM 2008/12/04 CHKD: THARYAMA 2008/12/04 APPR: NIKITA 2008/12/08 B	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
FINISH 仕上げ	注記参照 SEE NOTES			10 UNDER ±0.2	DRAWN BY M. NAGATA	DATE 2004/03/09	TITLE EMBOSSD TAPE PACKAGE FOR 55650-***81 -LEAD FREE-		
WIPE RANGE 適用電線範囲	—			10 OVER 30 UNDER ±0.25	CHECKED BY K. TOJO	DATE 2004/03/09	MOLEX INCORPORATED		
INS. RANGE 被覆外径	—			30 OVER ±0.3	APPROVED BY M. SASAO	DATE 2004/03/09	MATERIAL NO. SEE SHEET 2	DOCUMENT NO. SD-55650-014	SHEET NO. 1 OF 2
				ANGULAR ±3 °		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					

10 9 8 7 6 5 4 3 2 1



37.5	33.4	32±0.3	28.4	20.45	14.2	18.05	55650-0788	70
				17.95		15.55	55650-0688	60
29.4	25.4	24±0.3		15.45	11.5	13.05	55650-0588	50
				12.95		10.55	55650-0488	40
				10.45		8.05	55650-0388	30
21.4	17.4	16±0.3		7.95	7.5	5.55	55650-0288	20
G	F	E	D	(C)	(B)	(A)	製品番号 MATERIAL NO.	極数 CIRCUITS

累積ピッチ: 40±0.2
ACUUMLATIVE PITCH: 40±0.2

MODEL NO. 55650-**88

MATERIAL 材料	注記参照 SEE NOTES	REVISED	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
FINISH 仕上げ	注記参照 SEE NOTES	EC NO: J2009-0552	2008/12/04	10 UNDER ±0.2	DRAWN BY M. NAGATA	DATE 2004/03/09	TITLE EMBOSSED TAPE PACKAGE FOR 55650-**81 -LEAD FREE-	
WIPE RANGE 適用電線範囲		DRW: YOSHIDAM	2008/12/04	10 OVER 30 UNDER ±0.25	CHECKED BY K. TOJO	DATE 2004/03/09	MOLEX INCORPORATED	
INS. RANGE 被覆外径		CHKD: THARYAMA	2008/12/08	30 OVER ±0.3	APPROVED BY M. SASAO	DATE 2004/03/09	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-55650-014
				ANGULAR ±3 °	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-55650-014	SHEET NO. 2 OF 2
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			